

3A Avg.

65 Volts

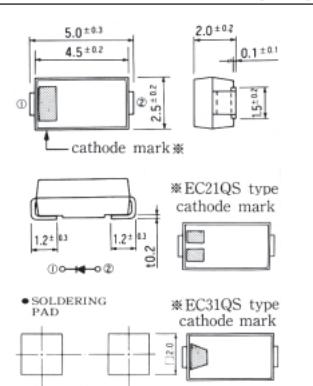
SBD

EC30QSA065

■最大定格 Maximum Ratings

Item	Symbol	Conditions			Unit
くり返しピーク逆電圧 Repetitive Peak Reverse Voltage	V _{RRM}	65			V
平均整流電流 Average Rectified Forward Current	I _O	50Hz、正弦半波通電抵抗負荷 50Hz Half Sine Wave Resistive Load	T _a =26°C* V _{RM} =30V	1.6	A
			T _j =92°C V _{RM} =30V (T _j :Lead Temperature)	3.0	A
実効順電流 R.M.S. Forward Current	I _{F(RMS)}	4.71			A
サージ順電流 Surge Forward Current	I _{FSM}	60	50Hz正弦半波、1サイクル、非くり返し 50Hz Sine Wave,1cycle, Non-repetitive		A
動作接合温度範囲 Operating Junction Temperature Range	T _{jw}	-40~+150			°C
保存温度範囲 Storage Temperature Range	T _{stg}	-40~+150			°C

■OUTLINE DRAWING(mm)



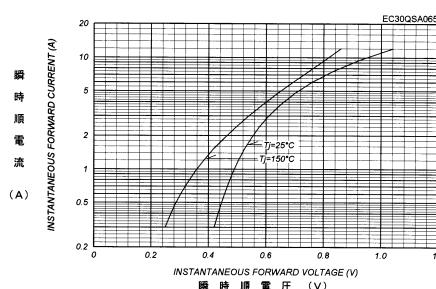
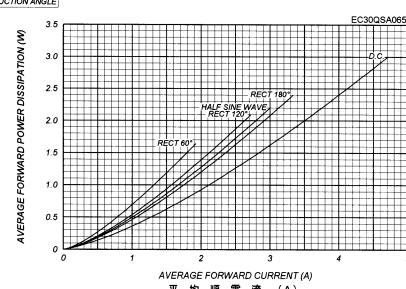
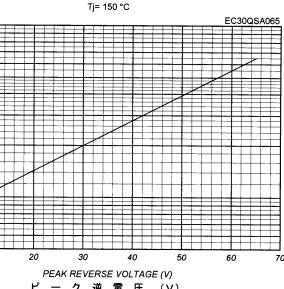
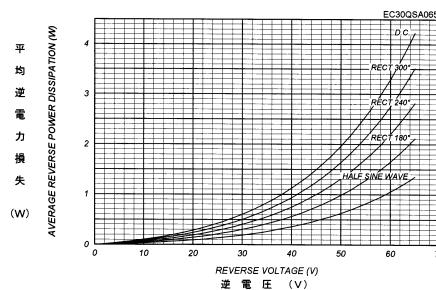
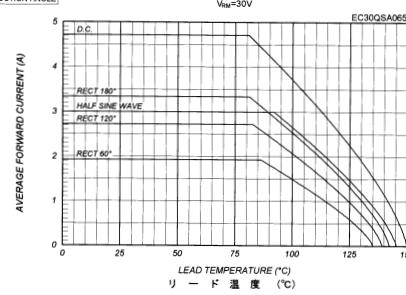
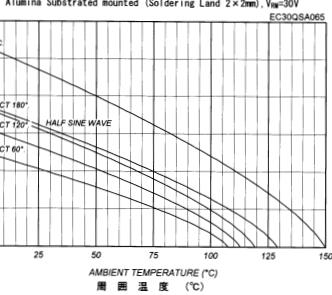
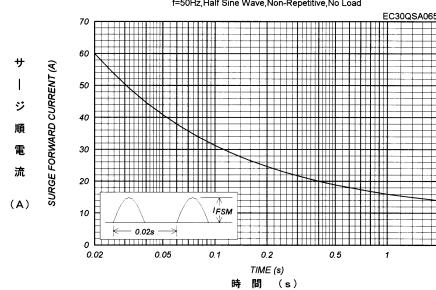
■APPROX. NET WEIGHT:0.06 g

■電気的・熱的特性 Electrical/Thermal Characteristics

Item	Symbol	Conditions		Min.	Typ.	Max.	Unit
ピーカー逆電流 Peak Reverse Current	I _{RM}	T _j =25°C, V _{RM} =65V		—	—	300	μA
ピーカー順電圧 Peak Forward Voltage	V _{FM}	T _j =25°C, I _{FM} =3A		—	—	0.61	V
熱抵抗 Thermal Resistance	R _{th(j-a)}	接合部・周囲間 Junction to Ambient	* (アルミナ基板実装)	—	—	108	°C/W
	R _{th(j-l)}	接合部・リード間 Junction to Lead	—	—	—	23	°C/W

* アルミナ基板実装/Alumina Substrate mounted (Soldering Lands= 2 × 2 mm , Both Sides)

■定格・特性曲線

FIG.1
順電圧特性
FORWARD CURRENT VS. VOLTAGECONDUCTION ANGLE
0° ~ 180°FIG.2
平均順電力損失特性
AVERAGE FORWARD POWER DISSIPATIONFIG.3
ピーカー逆電流 - ピーカー逆電圧特性
PEAK REVERSE CURRENT VS. PEAK REVERSE VOLTAGEFIG.4
平均逆電力損失
AVERAGE REVERSE POWER DISSIPATIONCONDUCTION ANGLE
0° ~ 180°FIG.5
平均順電流リード温度定格
AVERAGE FORWARD CURRENT VS. LEAD TEMPERATURECONDUCTION ANGLE
0° ~ 180°FIG.6
平均順電流一回路温度定格
AVERAGE FORWARD CURRENT VS. AMBIENT TEMPERATUREFIG.7
サージ順電流定格
SURGE CURRENT RATINGSFIG.8
接合容量特性
JUNCTION CAPACITANCE VS. REVERSE VOLTAGE